N3T080MP330 3300 V 80 mΩ Silicon Carbide MOSFET

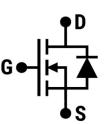
V _{DS}	I _D	R _{DS(on)}	Package
3300 V	34 A	80 mΩ	Bare Die

Features

- State-of-the-art SiC MOSFET technology
- · Reliable gate oxide process
- · Ultra-low output capacitance
- Best-in-class figure-of-merits, $[R_{on} * C_{oss}]$ and $[R_{on} * C_{res}]$
- Stable switching characteristics up to 175 °C

Benefits

- · Higher system efficiency
- · Reduced cooling requirements
- · Increased power density
- · Increased system switching frequency
- · Enhanced system reliability
- · Reduced total harmonic distortion





Applications

- Motor drives
- · Solar PV inverters
- · EV onboard chargers
- · Server power supplies
- Energy storage systems
- EV fast charging stations
- · Solid-state power controllers
- · Uninterruptible power supplies

Maximum Ratings

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	Note
Drain-Source Voltage	V _{(BR)DSS}	T _C = 25 °C	3300	-	-	V	
Gate-Source Voltage	V _{GS(max)}		-10	-	25	v	
	V _{GS,op}	Recommended Operation	-	-5/+20	•		
Continuous Drain Current	I _D -	V _{GS} = 20 V, T _C = 25 °C	-	•	34	Α	Fig.
		V _{GS} = 20 V, T _C = 100 °C	-	•	24		13
Pulsed Drain Current	I _{D(pulse)}	T _C = 25 °C	•	•	80	A	Fig. 12
Power Dissipation	P _{tot}	T _C = 25 °C	-	•	288	W	Fig. 14
Operating and Storage Temperature	T_{J},T_{stg}		-55		175	°C	

Thermal and Bare Die Characteristics

Parameter	Symbol	Comment	Min.	Тур.	Max.	Unit	Note
Thermal Resistance, Junction to Case	R _{thJC}	Based on TO-247-4L packaged die measurements	-	0.32	0.52	°C/W	Fig. 11
Thermal Resistance, Junction to Ambient	R _{thJA}	Based on TO-247-4L packaged die measurements	-	•	40	°C/W	
Bare Die Thickness	W _{die}		335	360	385	μm	
Top Metal Thickness	w _{top}	Al/Cu metallization	•	5.0	ı	μm	
Bottom Metal Thickness	W _{bottom}	Ag metallization	-	1.0	-	μm	_

<u>Electrical Characteristics</u> ($T_c = 25$ °C unless otherwise specified)

STATIC CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	Note
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 100 μA	3300	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 3300 V, V _{GS} = 0 V	-	1	100	μΑ	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}$, $I_D = 10 \text{ mA}$	1.8	2.5	3	v	
Gate-Source Leakage Current	I _{GSS}	V _{GS} = -10 / +25 V, V _{DS} = 0 V	•	1	±100	nA	
Transconductance	g_{fs}	V _{DS} = 10 V, I _D = 20 A	-	9.8	ı	S	Fig. 8
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 20 V, I _D = 20 A	-	79	90	mΩ	Fig. 1
		V _{GS} = 20 V, I _D = 20 A, T _C = 175 °C	-	252	-	mΩ	Fig. 3
		V _{GS} = 18 V, I _D = 20 A	-	81	-	mΩ	Fig. 1
		V _{GS} = 18 V, I _D = 20 A, T _C = 175 °C	-	253	-	mΩ	Fig. 3

DYNAMIC CHARACTERISTICS

Note: Based on TO-247-4L packaged die measurements

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	Note
Input Capacitance	C _{iss}		-	3830	-	pF	Fig. 10
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 1700 V, V _{AC} = 25 mV, f = 100 kHz	-	53.5	-		
Reverse Capacitance	C _{rss}		-	3.35	-		
Gate-Source Charge	Q _{GS}		-	30	-	nC	Fig. 15
Gate-Drain Charge	Q_{GD}	V _{DS} = 1700 V, V _{GS} = -5 / +20 V, I _D = 20 A	-	28	-		
Total Gate Charge	Q_{G}	. 63	-	168	-		
Internal Gate Resistance	R _{G(int)}	V _{AC} = 25 mV, f = 1 MHz	-	1.1	-	Ω	
Turn-On Switching Energy	E _{on}	V ₂₂ = 1700 V. I ₂ = 20 A.	-	1283	-	μJ	Fig. 16 Fig. 17 Fig. 18
Turn-Off Switching Energy	E _{OFF}	$ \begin{array}{c} V_{DD} = 1700 \text{ V, } I_{D} = 20 \text{ A,} \\ V_{GS} = -5 \text{ / } +20 \text{ V, } R_{G(ext)} = 10 \\ \Omega, \end{array} $	-	217	-		
Total Switching Energy	E _{тот}	L = 500 μH	-	1500	-		1 ig. 10
Turn-On Delay Time	t _{d(on)}	V = 1700 V I = 20 A	-	43	-		
Rise Time	t _r	$\begin{array}{l} V_{DD} = 1700 \text{ V, I}_{D} = 20 \text{ A,} \\ V_{GS} = -5 \text{ / } +20 \text{ V, R}_{G(ext)} = 10 \\ \Omega, \\ L = 500 \mu\text{H} \\ \text{Timing relative to V}_{DS} \\ \text{Inductive Load} \end{array}$	-	29	-		Eig 40
Turn-Off Delay Time	t _{d(off)}		-	74	•	ns	Fig. 19
Fall Time	t,		-	22	-		

BODY DIODE CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	Note
Diode Forward Voltage	v	V _{GS} = -5 V, I _{SD} = 20 A	•	4.8	•	٧	Fig. 20
	V _{SD}	V _{GS} = -5 V, I _{SD} = 20 A, T _J = 175 °C		4.1	-	٧	Fig. 21
Continuous Diode Forward Current	I _s	V _{GS} = -5 V	-	44	-	Α	
Reverse Recovery Time	t _{rr}		-	9	-	ns	
Reverse Recovery Charge	Q _{rr}	V _R = 1700 V, I _{SD} = 20 A, V _{GS} = -5 V, di _F /dt = 1000 A/μs	-	226	-	nC	
Peak Reverse Recovery Current	I _{RRM}		-	25	-	Α	

Typical Performance

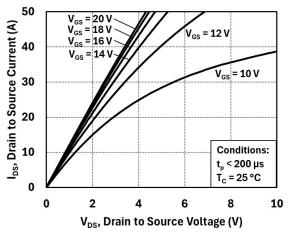


Figure 1: Output Characteristics at 25 °C

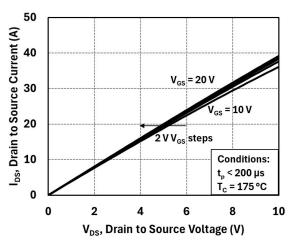


Figure 3: Output Characteristics at 175 °C

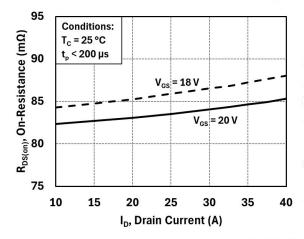


Figure 5: On-Resistance vs. Drain Current

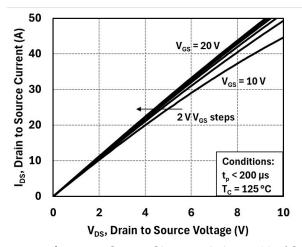


Figure 2: Output Characteristics at 125 °C

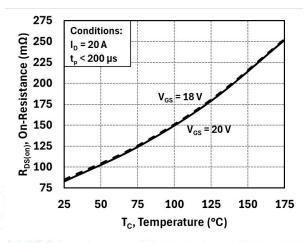


Figure 4: On-Resistance vs. Temperature

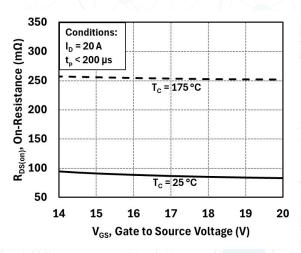


Figure 6: On-Resistance vs. Gate Voltage

Typical Performance

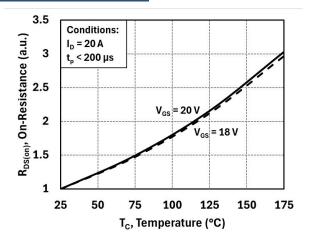


Figure 7: Normalized On-Resistance vs. Temperature

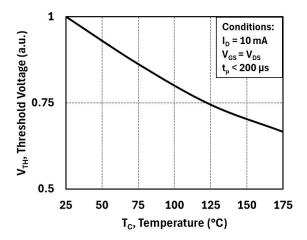


Figure 9: Threshold Voltage vs. Temperature

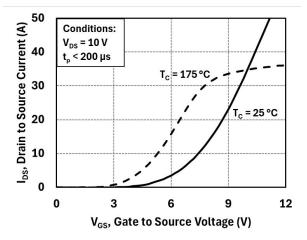


Figure 8: Transfer Characteristics

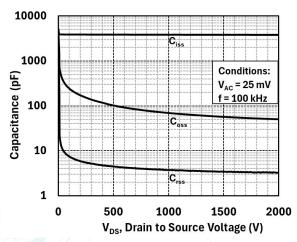


Figure 10: Capacitances vs. Drain-Source Voltage (0-1000 V)

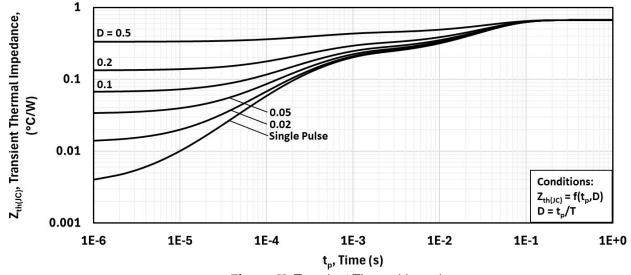


Figure 11: Transient Thermal Impedance

Typical Performance

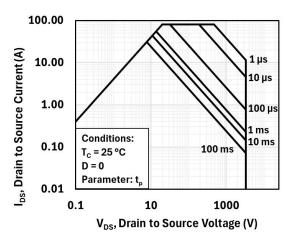


Figure 12: Safe Operating Area

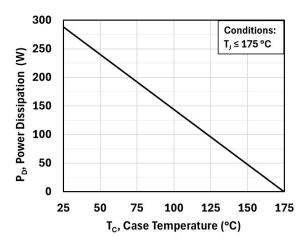


Figure 14: Power De-rating Curve

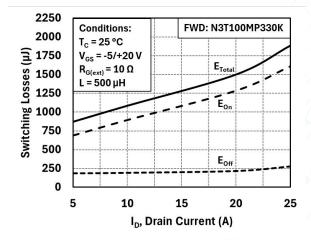


Figure 16: Inductive Switching Energy vs. Drain Current $(V_{DD} = 1700 \text{ V})$

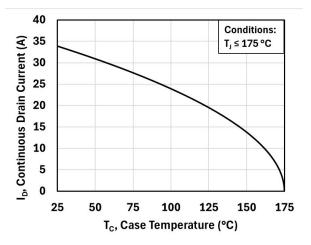


Figure 13: Current De-rating Curve

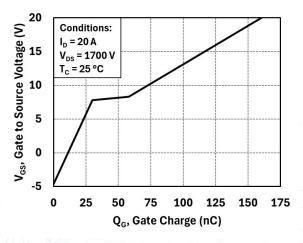


Figure 15: Gate Charge Characteristics

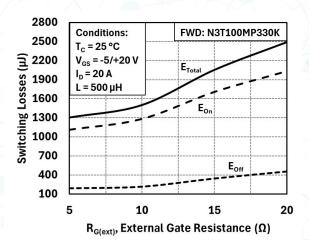


Figure 17: Inductive Switching Energy vs. $R_{G(ext)} (V_{DD} = 1700 \text{ V})$

NOVEL MATERIALS AND INNOVATIVE SEMICONDUCTORS

Typical Performance

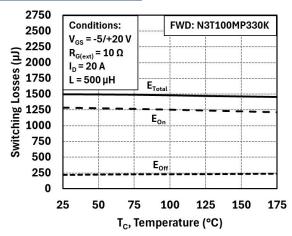


Figure 18: Inductive Switching Energy vs.

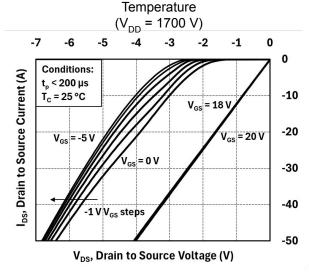


Figure 20: Body Diode Characteristics at 25 °C

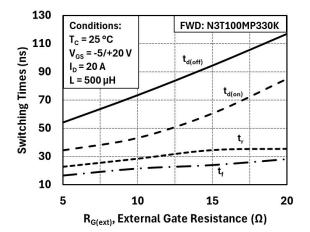


Figure 19: Switching Times vs.

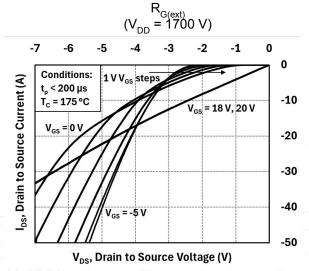


Figure 21: Body Diode Characteristics at 175 °C

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Dynamic Testing Circuit Schematics

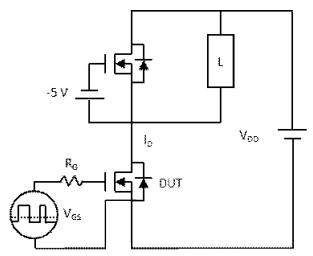


Figure 22: Inductive Load Switching Test Circuit

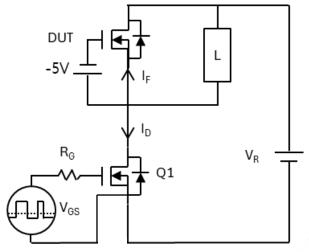


Figure 24: Reverse Recovery Test Circuit

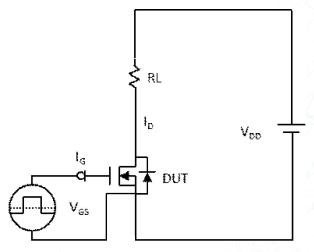


Figure 26: Gate Charge Test Circuit

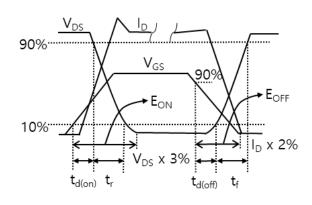


Figure 23: Inductive Load Switching Test Waveforms

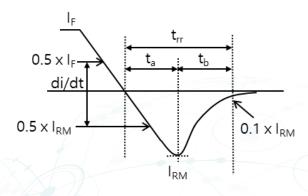
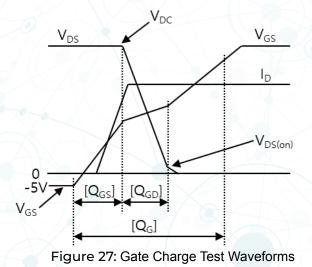
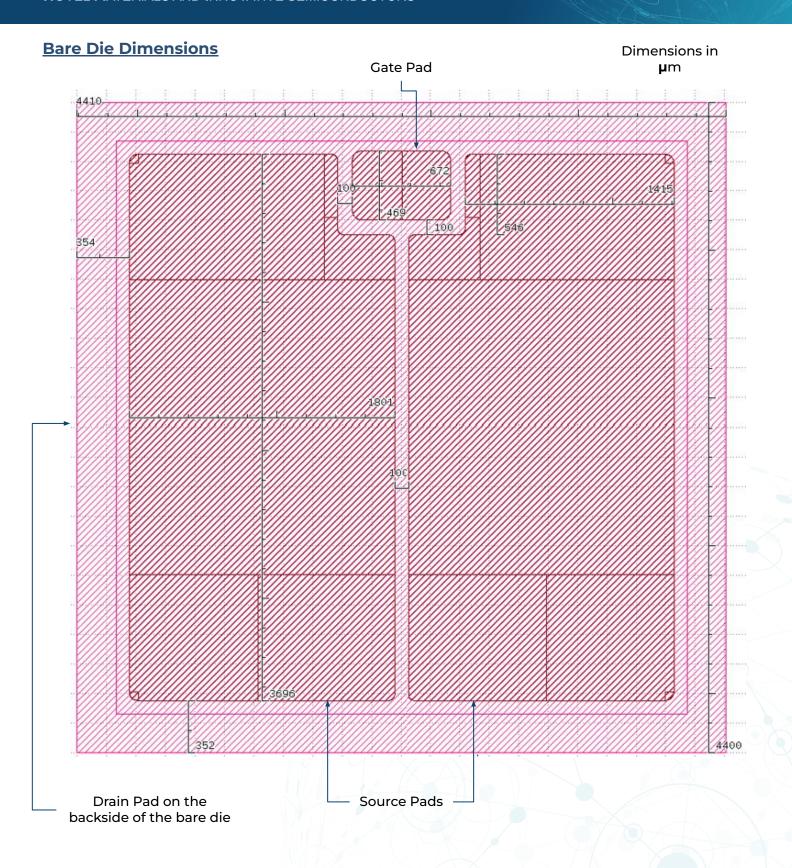


Figure 25: Body Diode Reverse Recovery Test Waveforms





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